

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2596349

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>TOSHIYA KOBAYASHI</td> <td>10/18/2013</td> </tr> <tr> <td>TOSHIKI IIZUKA</td> <td>10/16/2013</td> </tr> </tbody> </table>		Name	Execution Date	TOSHIYA KOBAYASHI	10/18/2013	TOSHIKI IIZUKA	10/16/2013
Name	Execution Date						
TOSHIYA KOBAYASHI	10/18/2013						
TOSHIKI IIZUKA	10/16/2013						
RECEIVING PARTY DATA							
Name:	SUNTORY HOLDINGS LIMITED						
Street Address:	1-40, DOJIMAHAMA 2-CHOME, KITA-KU						
City:	OSAKA-SHI, OSAKA						
State/Country:	JAPAN						
Postal Code:	530-8203						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14112560</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14112560		
Property Type	Number						
Application Number:	14112560						
CORRESPONDENCE DATA							
Fax Number:	(202)595-0530						
Phone:	202-842-8800						
Email:	dcpatentfiling@dbr.com						
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>							
Correspondent Name:	DRINKER BIDDLE & REATH (DC)						
Address Line 1:	1500 K STREET, N.W.						
Address Line 2:	SUITE 1100						
Address Line 4:	WASHINGTON, DISTRICT OF COLUMBIA 20005-1209						
ATTORNEY DOCKET NUMBER:	047635-0059-00-US-502395						
NAME OF SUBMITTER:	MERCEDES K. MEYER						
Signature:	/Mercedes K. Meyer/						
Date:	10/30/2013						
Total Attachments: 1 source=047635_0059_assignment#page1.tif							

OP \$40.00 14112560

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

METHOD FOR PRODUCING RESIN BOTTLES

for which I/WE are filing an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on _____, (Serial No. _____); and

WHEREAS, SUNTORY HOLDINGS LIMITED, a corporation of Japan, whose post office address is 1-40, Dojimahama 2-chome, Kita-ku, Osaka-shi, Osaka 530-8203 Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application or any application claiming priority based on this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, or any application claiming priority based on this application, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, or any application claiming priority based on this application, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Toshiya KOBAYASHI	Assignor's Signature TOSHIYA KOBAYASHI	Date Oct. 18, 2013
Address: 2-3-3, Daiba, Minato-ku Tokyo, Japan		Citizenship JP
Full Name of Second Assignor Toshiaki IIZUKA	Assignor's Signature TOSHIAKI IIZUKA	Date Oct. 16, 2013
Address: 2-3-3, Daiba, Minato-ku Tokyo, Japan		Citizenship JP

Names of additional inventors attached Yes No